(International Annealed Copper Standard) or more. The target value of heat resistance is determined by consideration for taking soldering with electronic parts or thermal fusion-bonding with the liquid crystal polymer. The thermal resistance is defined by the value of the heating temperature, at which the tensile strength after heating for 1 hour is reduced to an intermediate level between that of prior to heating and that after fully annealed. The target value of heating temperature is 350°C or more. --

Please replace the paragraph beginning on page 9, lines 4-8, with the following rewritten paragraph:

--(4) Heat Resistance. Heating is carried out at a predetermined temperature for 1 hour. Tensile strength is then measured at room temperature. The heating temperature, at which the measured tensile strength is intermediate between that prior to heating and the heated and fully softened tensile strength is identified as the softening temperature. --

IN THE CLAIMS:

Please amend the claims as follows:

1. (Amended) A copper-alloy foil used for a laminate sheet, which contains, by weight percentage, one or more of from 0.01 to 2.0% of Cr and from 0.01 to 1.0% of Zr, the balance being copper and unavoidable impurities, and which comprises on the outermost surface, an oxide layer and a rust-proof film which taken

together are greater than 0 nm up to and including 10 nm in thickness, and 50%IACS or more of electrical conductivity, and 5.0N/cm or more of 180° peeling strength when thermally fusion-bonded with a liquid crystal polymer.

2. (Amended) A copper-alloy foil used for a laminate sheet, which contains, by weight percentage, one or more of from 0.01 to 2.0% of Cr and from 0.01 to 1.0% of Zr, and which further contains from 0.005 to 2.5% in total of at least one element selected from the group consisting of Ag, Al, Be, Co, Fe, Mg, Ni, P, Pb, Si, Sn, Ti and Zn, the balance being copper and unavoidable impurities, and comprises on the outermost surface, an oxide layer and a rust-proof film which taken together are greater than 0nm up to and including 10 nm in thickness, and 50%IACS or more of electrical conductivity, and 5.0N/cm or more of 180° peeling strength when thermally fusion bonded with a liquid crystal polymer.

3. (Amended) A copper-alloy foil according to claim 1 or 2, which has been heated to 350°C or higher for 1 hour, so the tensile strength is intermediate between that prior to heating and that after fully annealed.

4. (Amended) A laminate sheet of a copper-alloy foil and liquid crystal polymer thermally fusion-bonded without a binder, wherein said copper-alloy foil contains, by weight percentage, one or more of from 0.01 to 2.0% of Cr and from 0.01 to 1.0% of Zr, the balance being copper and unavoidable impurities, and comprises on the outermost surface, an oxide layer and a rust-proof film which taken together are greater than 0nm up to and including 10nm in thickness, and 50%IACS or more of electrical conductivity, and 5.0N/cm or more of 180° peeling strength when thermally fusion bonded with a liquid crystal polymer.

A3

5. (Amended) A laminate sheet of a copper-alloy foil and liquid crystal polymer thermally fusion-bonded without a binder, wherein said copper-alloy foil contains, by weight percentage, one or more of from 0.01 to 2.0% of Cr and from 0.01 to 1.0% of Zr, and further contains from 0.005 to 2.5% in total of at least one element selected from the group consisting of Ag, Al, Be, Co, Fe, Mg, Ni, P, Pb, Si, Sn, Ti and Zn, the balance being copper and unavoidable impurities, and comprises on the outermost surface, an oxide layer and a rust-proof film which taken together are greater than 0nm up to and including 10nm in thickness, and 50%IACS or more of electrical conductivity, and 5.0N/cm or more of 180° peeling strength when thermally fusion bonded with a liquid crystal polymer.